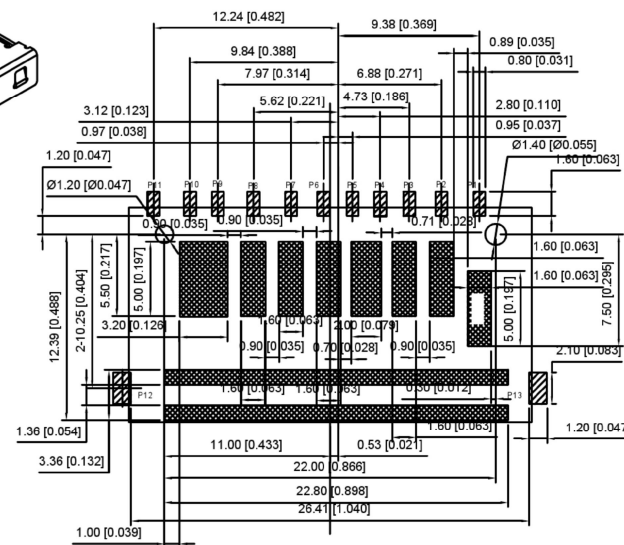
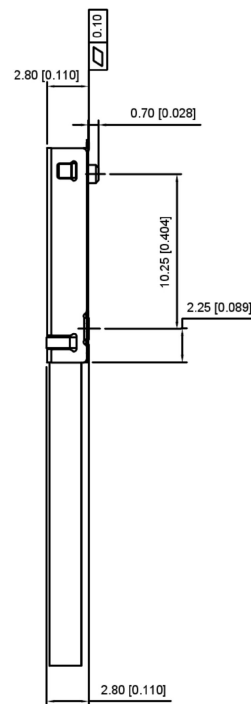
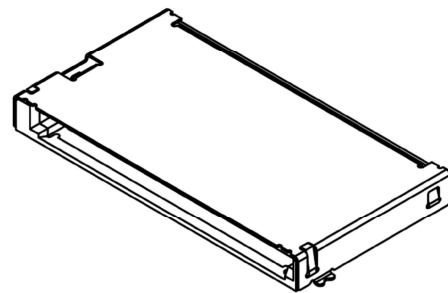




 PAD

 No trace , no test point,
no via hole, no ground area

WITHOUT CARD	CARD INSERTED: LOCK	CARD INSERTED: UNLOCK
W/P GND	W/P GND	W/P GND
C/D VSS1 P3	C/D VSS1 P3	C/D VSS1 P3

Pin Define		
Connector Pin No.	SD Card Pin No.	Pin Define
P1	P9	DAT2
P2	P1	DAT3
P3		CMD
P4		CD
P5	P3	VSS1
P6	P4	VDD
P7	P5	CLK
P8	P6	VSS2
P9	P7	DAT0
P10	P8	DAT1
P11		WP
P12-P13		GND

- *电气特性 Electrical Characteristics:
 - 触点额定电流 Contact Current Rating:0.5 Amperes.
 - 绝缘耐压 Dielectric Withstanding Voltage:AC500V r.m.s.
 - 绝缘电阻 Insulation Resistance:1000 MΩ Minimum.
 - 接触电阻 Contact Resistance:100 mΩ Maximum.
- *环境 Environmental:
 - 操作温度 Operating Temperature:-25°C~+85°C.
- *机械特性 Mechanical Characteristics:
 - 寿命 Mating Cycles:10,000 Cycles Insertion/Extraction
 - 卡推插/拔出力 Card Push Insertion/Out Force:1kgf Maximum.
 - 端子保持力 Contact Retention Force:0.15kgf Minimum.
- *材料 Material:
 - 隔热材料 Insulator:HI-Temp Plastic UL 94V-O Rated.
 - 触点 Contact:Copper Alloy.
 - 外壳 Shell:Stainless Steel.

						DSND		SCALE: N/A	MODEL TYPE: SIM CARD CONN		
						DWN		VIEW: 	PART NO.: XKSD-1250-DS28		
						CHKD		UNIT: mm/in	DWG NO.:		
						APPD		SIZE: A4			
				ANGLAR	±5°	DONG GUAN XI BANG ELECTRONIC CO., LTD					
				L ≤ 4	±0.2						
				4 < L ≤ 16	±0.3						
				16 < L ≤ 63	±0.4						
				L > 63	±0.5						
REVISIONS				UNSPECIFIED TOLERANCES		DONG GUAN XI BANG ELECTRONIC CO., LTD					
www.alpsr.com www.gdxjdz.com www.xbswitch.com											
	DATE	REVISED	APPROVED			WEIGHT	SHEET	REVISION			
							1/1	A0			